CHEMTRONICS® Technical Data Sheet

TDS # CWF8

Chemask® WF Solder Masking Agent

PRODUCT DESCRIPTION

Chemask® WF Solder Masking Agent is water soluble and designed to be removed with most aqueous cleaning systems. Chemask® WF Solder Masking Agent contains high temperature compounds that protect component-free areas from solder during wave soldering. This water soluble formulation is stable to rosin, organic and inorganic fluxes.

- Protects boards from molten solder to 515°F (268°C)
- Compatible with most flux types
- Leaves no corrosive residue
- Non-contaminating
- UV detectable

TYPICAL APPLICATIONS

During wave soldering, Chemask® WF Solder Masking Agent protects:

- Component Free Areas
- Gold Connectors
- Gold Fingers
- Pin Connectors

TYPICAL PRODUCT DATA AND PHYSICAL PROPERTIES

Base Material	Synthetic Resin
Color	Tan
Solvent Stability	Dissolves in water with
	or without detergent
Flux Compatibility	Aqueous Flux
Temperature Stability	515°F (268°C)
Tack-Free Drying Time	e 30 min.
(10 mils @ 77°F)	
Cure Time	1 hr.
(10 mils @ 77°F)	
Viscosity (@ 77°F)	9,000 cps
(± 300 cps)	
Viscosity Adjusted Wit	h DI Water
Contains UV Indicator	Yes
Solids Content	~ 40%
Flash Point	Nonflammable
Weight/Gallon	8.8 lbs.

COMPATIBILITY

Chemask® WF Solder Masking Agent is generally compatible with most materials used in printed circuit board fabrication. As with any solder masking agent, compatibility with substrate must be determined on a non-critical area prior to use.